

### Moisture Barrier ESD Bags

#### DESCRIPTION

Moisture Barrier Bags are designed for the packing of SMDs; protecting them from moisture and static damage. Moisture Barrier Bags protect electronics from moisture and static damage during storage and transportation. These bags are ideal for storing static sensitive devices in humid environments. Moisture Barrier Bags are Jedec compliant; enabling you to safely transport Jedec Trays. Each bag has a layer of aluminum that blocks the moisture. All bags should be used with a humidity indicator card and desiccant.

The bags are opaque and light-tight ensuring the contents cannot be seen from the outside; adding a layer of operational security. Our Moisture Barrier Bags are suitable for packing electronic products which are sensitive to moisture and static e.g. PCBs or integrated circuits. The 4mil puncture-resistant and moisture-proof packaging has a flexible structure and is suitable for vacuum-sealing. All bags are supplied in packs of 100pcs and as standard have the ESD symbol printed on the bags.

**Note:** Before each use, ensure that there are no wrinkles or surface scratch, damage or pin holes. All bags should be used with a humidity indicator card and desiccant.

#### FEATURES AND BENEFITS

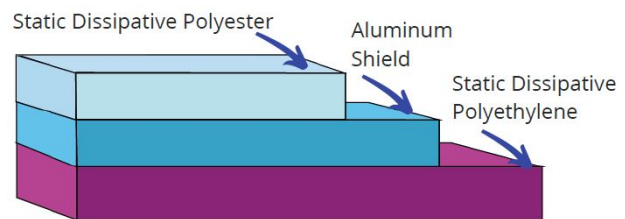
- Protects electronics from moisture and static damage during storage and transportation.
- Ideal for storing static sensitive devices in humid environments.
- Jedec compliant, allowing you to safely transport Jedec Trays.
- Manufactured from a layer of aluminum that blocks the moisture.
- Bags are heat-sealable with 'Faraday Cage' protection.
- Bags are vacuum-sealable and opaque.
- The recommended temperature for welding 150-200°C.
- Ideal for PCB's or integrated circuits.
- Each bag is RoHS and REACH compliant.
- Bespoke sizes, thickness, printing and packaging solutions can be manufactured on request.



#### CONSTRUCTION

The 4mil puncture-resistant and moisture-proof packaging has a flexible structure and is suitable for vacuum-sealing.

Meets the requirements of the joint IPC/JEDEC J-STD-033, ANSI/ESD S20.20, STM11.31 2006, EIA541, MIL-B-81705C Type 1, IEC 61340-5-1, FTMS101, MTH2065, GB/T 1040, ISO 527-2, ASTM D639-03, ASTM D-638, GB/T 16578-96, ASTM D1938-02, ASTM D-1876-72.



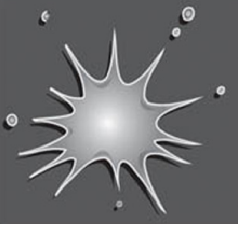
#### Electrical Properties:

Surface Resistivity / Resistance  
 Interior  
 Exterior  
 Static Shielding  
 Static Decay  
 Charge Retention

#### Typical Values

ANSI/ESD S11.11  
 $>10^{(6)} <10^{(11)}$  ohms/square  
 $>10^{(6)} <10^{(11)}$  ohms/square  
 $<30$  volts  
 $<50$  nj  
 $<2$  seconds  
 $<100$  volts

$>10^{(6)} <10^{(11)}$  ohms/square  
 $>10^{(6)} <10^{(11)}$  ohms/square  
 STM11.31  
 STM11.31.2006  
 IEC61340-5-1-1998  
 IEC61340-5-1-1998



# SOLDER CONNECTION

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## Appearance:

Clean

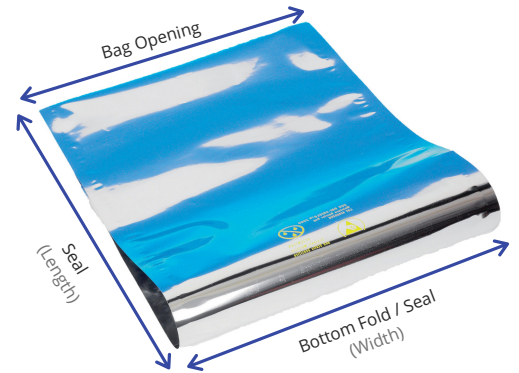
No wrinkle, surface scratch, damage, pin hole, delimitation, void. Pass  
 No separation on the encapsulation.

## Physical Properties

Peel Strength	≥0.5kg	
Heat Seal Strength	≥3.7kg	ASTM D-1876-72
WVTR Water Vapour	≤0.006 (ANSI/EIA 583)	ASTM F1249 (230c 90%RH)
Thickness	100micron (4 mils) +/- 10%	ISO 527-2:1993
OTR-Oxygen Transmission Rate	≤1.4cm <sup>3</sup> /(m <sup>2</sup> .24h.0.1MPa)	
Shelf Life	≥3 years	ASTM D3985
Puncture Strength	≥10.2kg	FTMS101, MTH2065
Burst Strength	146kg/cm <sup>2</sup> (2)	ASTM D-638
Snap Power	≥3.7kg	GB/T 1040-2006
(Vertical and Horizontal)		ISO 527-2:1993
Elongation Rate At Break	≥3.3kg	ASTM D-638
Tear Strength	≥0.6kg	GB/T 16578-96
(Vertical and Horizontal)	ASTM D1004-03	ASTM D1938-02

## AVAILABILITY

Reference	Size (inches)	Size (mm)
MOI1630	16" x 30"	152 x 762 mm
MOI1012	10" x 12"	254 x 305 mm
MOI1020	10" x 20"	254 x 508 mm
MOI1024	10" x 24"	254 x 610 mm
MOI1218	12" x 18"	305 x 457 mm
MOI1618	16" x 18"	406 x 457 mm
MOI1820	18" x 20"	457 x 508 mm



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